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Business Segment: ELECTRONICS

MACDERMID ALPHA TO PRESENT SOLDER PASTE SELECTION CHALLENGES FOR BOTTOM TERMINATION COMPONENTS (BTC) ATTACH AT CEIA IN CHENGDU CHINA

(Waterbury, CT USA) – May 22, 2019, the Assembly Division of MacDermid Alpha Electronics Solutions, a world leader in the production of electronic soldering and bonding materials, will be presenting a technical paper on “Solder Paste Selection Challenges for Bottom Termination Components (BTC) Attach” at China Electronics Intelligent Automation Conference (CEIA) in Chengdu China on May 29, 2019. This will be the first time to present our technical paper at CEIA.

Bottom Terminated Component (BTC) use has become extensive in electronic assembly, especially the use of Quad Flat No-lead (QFN) packages. Low cost and small size with improved thermal and electrical performance make BTC components very attractive for many applications.

Implementation of BTC components come with challenges. The low standoff, large central thermal pad and lack of leads result in co-planarity issues due to board warpage and Coefficient of Thermal Expansion (CTE) mismatch. Low standoff and a large central pad may favor increased voiding compared to other package designs. Therefore, in this paper, two solder paste chemistries and several printing parameters will be evaluated to achieve consistent solder paste deposition across the assembly.

For additional information about MacDermid Alpha’s latest technologies and products, please visit the MacDermidAlpha.com.

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